

**VERSION OF PARAGRAPH 2 ON PAGE 11 WITH MARKINGS TO SHOW
CHANGES**

Once the fine-line circuitization process as described above is complete, the process for forming a Surface Laminar Circuit (SLC) on either or both sides of the subcomposite is employed using a well-known method. The method for forming a printed circuit board having a surface laminar surface is fully described in U.S. Patent No. 5,097,593 and is hereby incorporated by reference herein. FIG. 12 shows printed circuit board 42 with the addition of photosensitive dielectric material 50. Additional circuitry ~~(not shown)~~ 60 may be formed on the surface of photosensitive dielectric 50 to produce a printed circuit board having a Surface Laminar Circuit on top of subcomposite 16. In such a case, vias are formed through photosensitive dielectric 50 such that the circuit lines ~~(not shown)~~ 60 on the photosensitive dielectric communicate with circuitry 40 and component pad 44 of subcomposite 16.